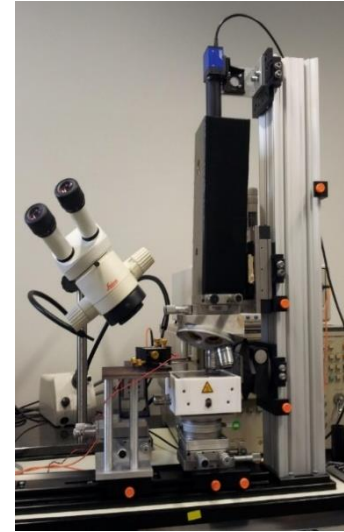
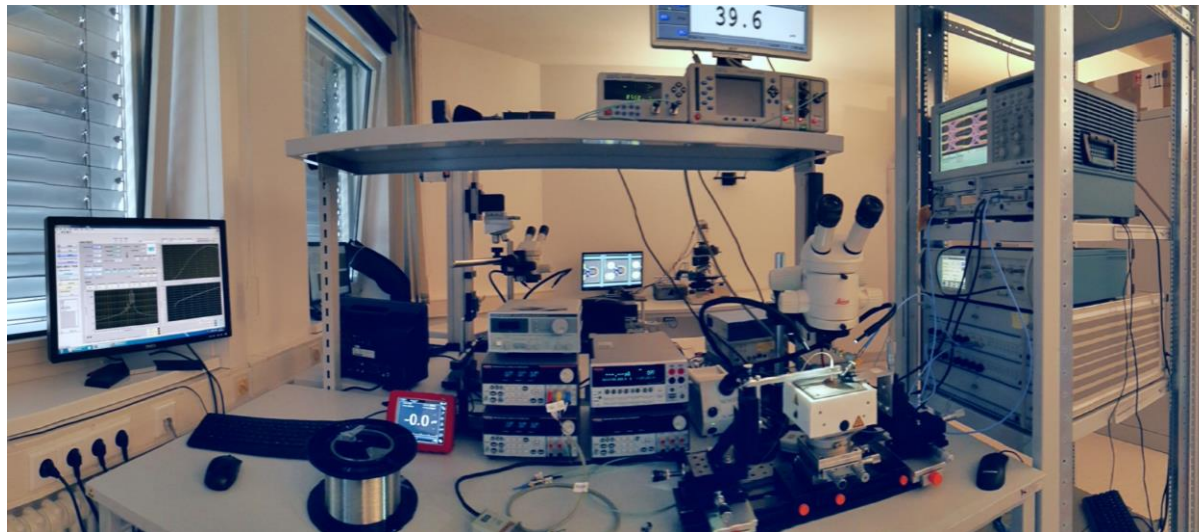


Vertically Integrated Systems

to serve strategic development and manufacturing needs



- 13 Years of technology excellence
- 22 issued & 3 pending patents
- 10 EU & National Projects won

2019: first ever 100G-compatible VCSEL
100G driver, 100G TIA, TX-RX assemblies

2019: strategic cooperation with a major III-V foundry (USA, Taiwan)
Customization
Contract manufacturing
Sales directly or through the foundry.

2016: >160 Gb/s 850nm VCSEL,
128Gb/s testbed, mapping

Qualified 850nm 28G VCSEL

2008: first ever 40G VCSEL
40G driver, 40G TIA
40G TX-RX assemblies

2017 Revenues 2.6 M€

2016 Investment 2.7 M€

2015 EU Horizon 2020 2M€

At break even since 2008

Support from Berlin (IBB, Berlin Partners)

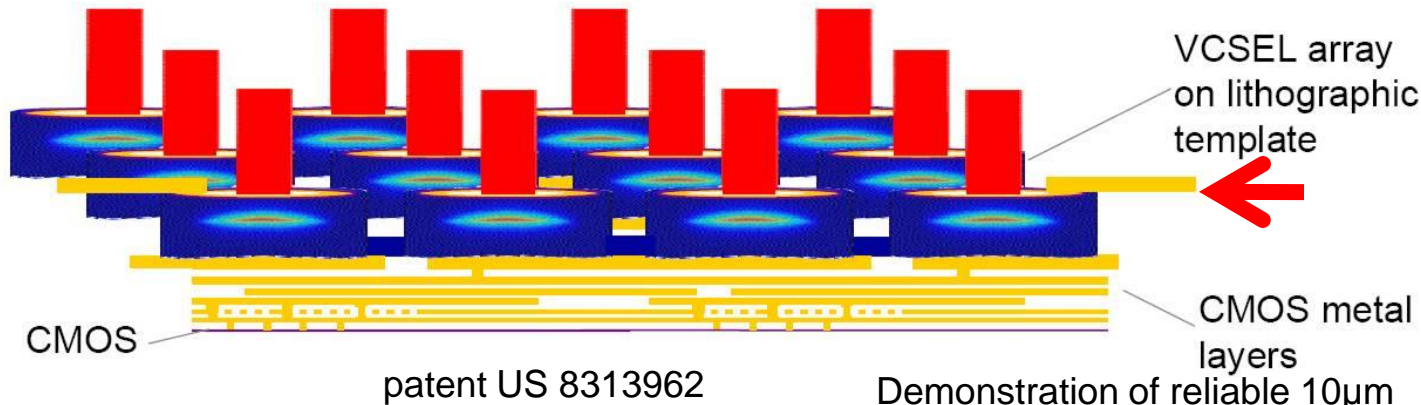
2007 VC Investment **1M€**

25G VCSEL

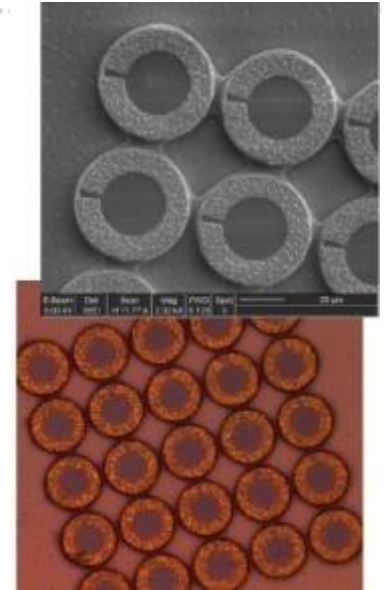
Est. Dec 2006



N. Ledentsov, J.A. Lott, invited talk at OFC 2009

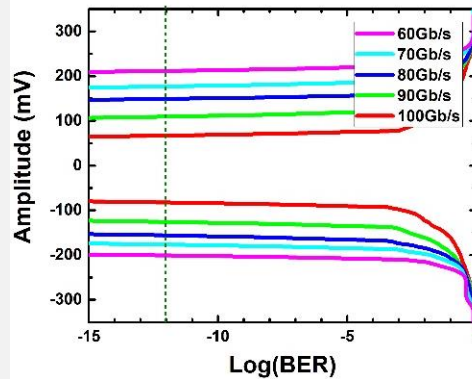
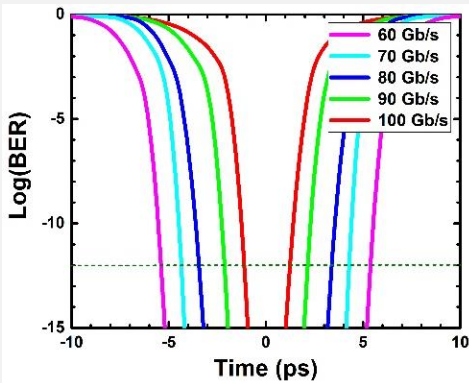


Demonstration of reliable 10µm VCSEL flakes
(SPIE 4649 203 (2002))



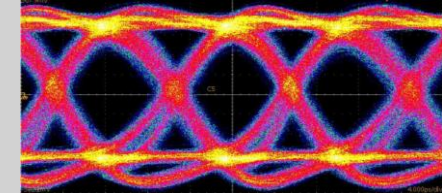
- Silicon scaling (5nm, 2019) drives I/O bandwidth: speed per channel doubles each 24 months, bandwidth density each 18 months
- 112Gb/s per channel copper is due 2020-2021 (Infiniband, Ethernet)
- Copper signaling over PCB becomes extremely expensive
- When I/O goes optical **trillions** of light-emitting devices will be needed in the upper IC levels, ...
- VCSEL: 25Gb/s at 180°C (850nm, VIS).
- VCSEL: size takes a few micrometers only, energy efficient, cost can be in milli-cents
- Upper level copper Interconnects do not scale and are not on CMOS surface. VCSEL lamination into IC or PCB is possible

VIS TX: VIS Driver + VIS TX VIS Amplifier



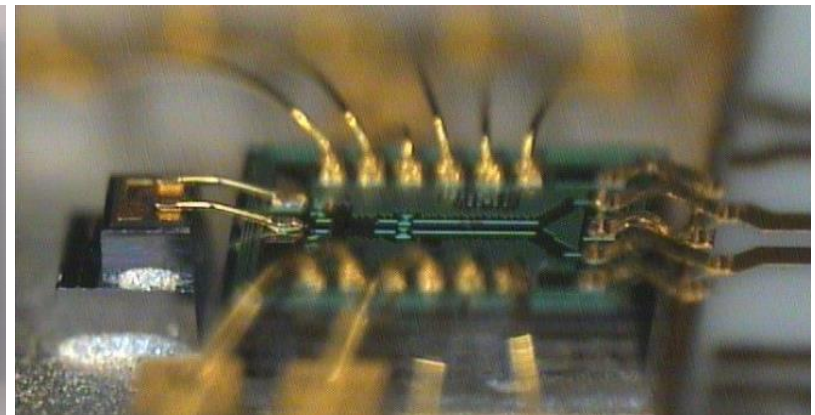
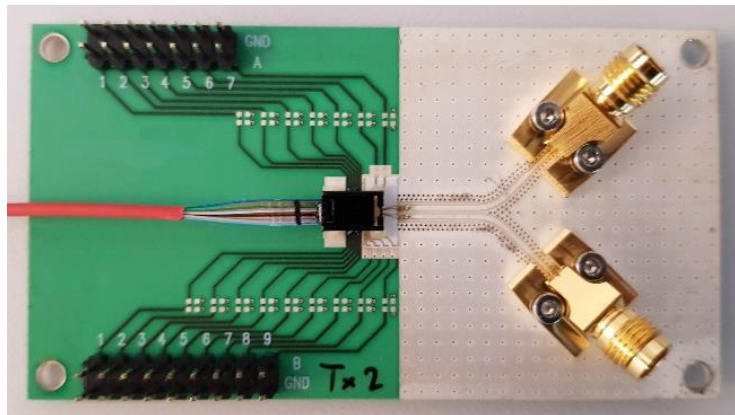
VCSEL Driver IC: error free up >90 Gbit/s

**90 Gb/s
setup limited**

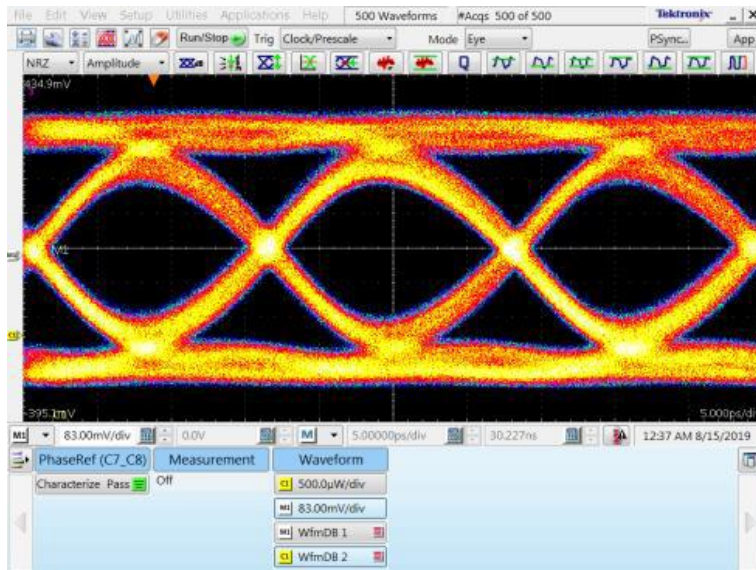


- Low current and low VCSEL capacitance results energy efficient electronics
- VIS ICs (amplifier + driver): 255 mW dissipated power per 100Gb/s link
- Good for >50Gb/s low latency links

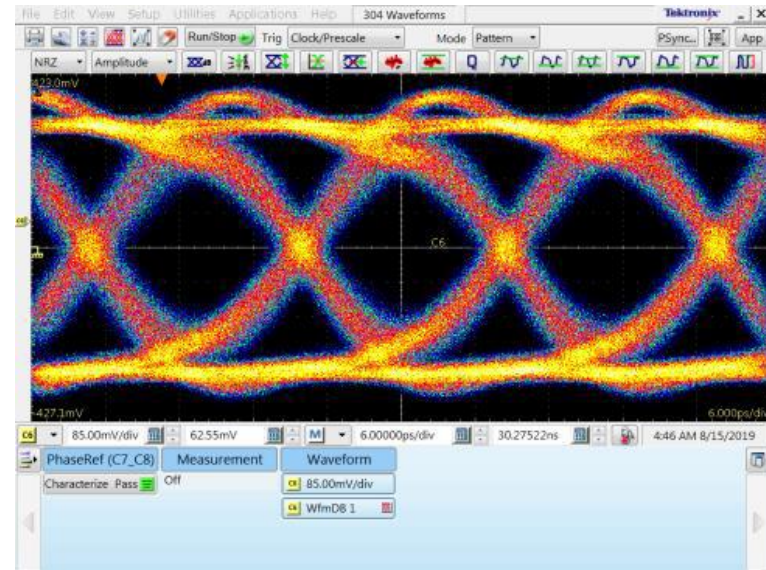
VIS transmitter (TX)/ VIS receiver (RX) Testboard:



60 Gbit/s TX-RX PRBS11 data transmission

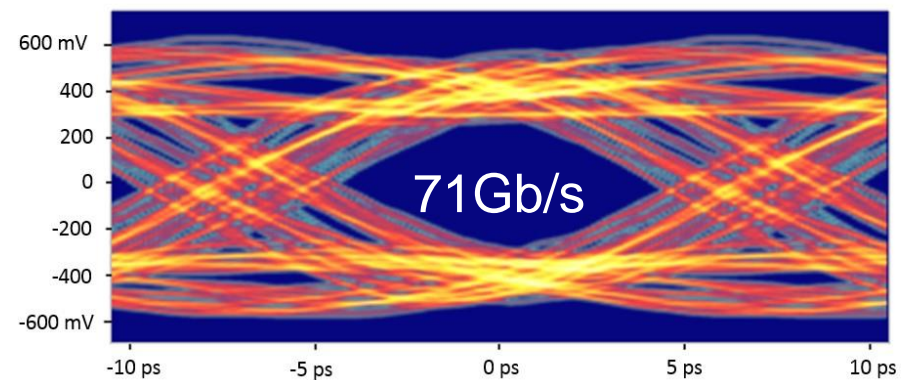


60Gbaud electrical input signal



60Gbaud VIS Transmitter/**VIS Receiver** link

- No equalization up to 70Gb/s
- No reclocking at the receiver
- Input signal is not corrected
- 6mW/Gbps vs 35mW/Gbps for IBM
- 2-tap equalization to get >70Gb/s



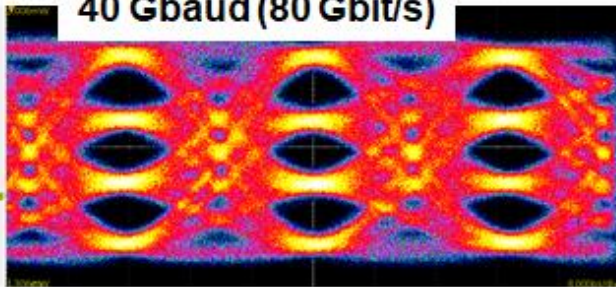
Attend VIS invited talks at OFC2020: D1 and D3 sections

120 Gbit/s PAM-4 VIS VCSEL Transmission

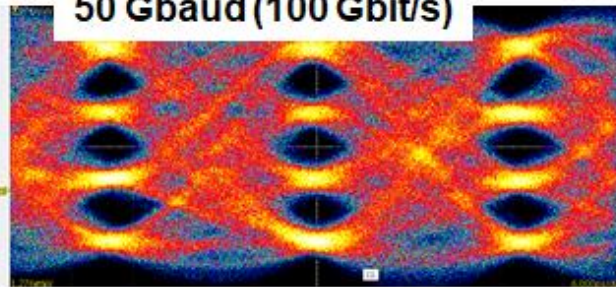
Tx: Keysight AWG w 6-tap FFE pre-emphasis

Rx: Tektronix Oscilloscope 30 GHz receiver w/o equalization

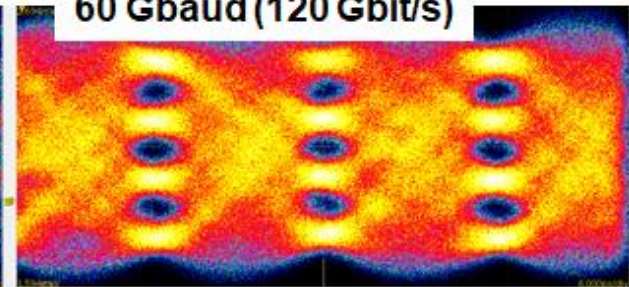
40 Gbaud (80 Gbit/s)



50 Gbaud (100 Gbit/s)

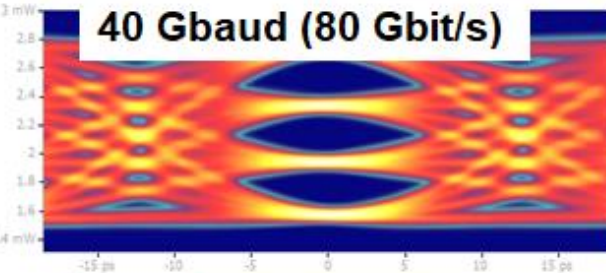


60 Gbaud (120 Gbit/s)

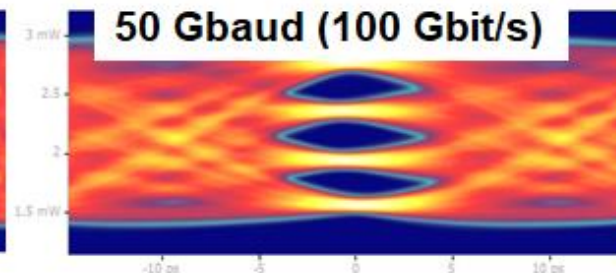


Tx: ... Rx: Tektronix Oscilloscope 30 GHz receiver w. 5-tap FFE equalization (like for copper)

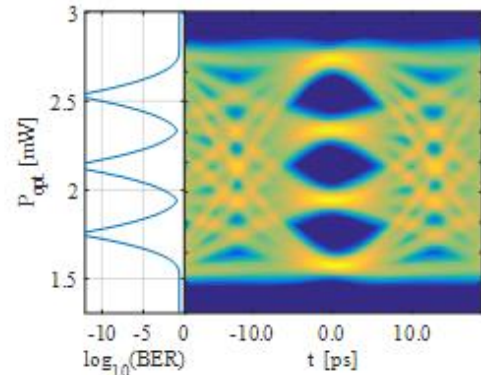
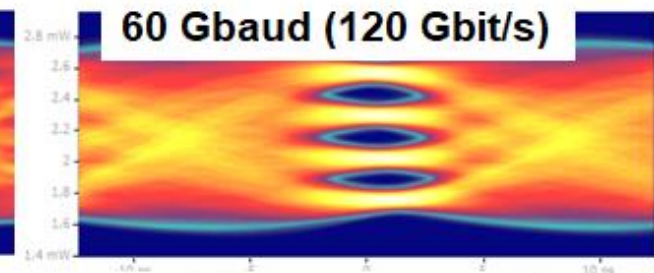
40 Gbaud (80 Gbit/s)



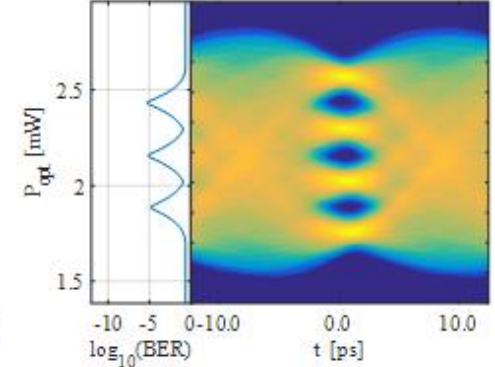
50 Gbaud (100 Gbit/s)



60 Gbaud (120 Gbit/s)



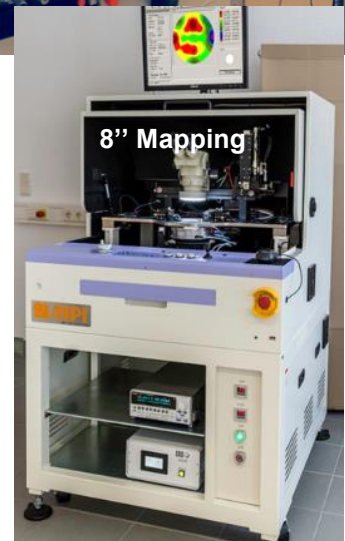
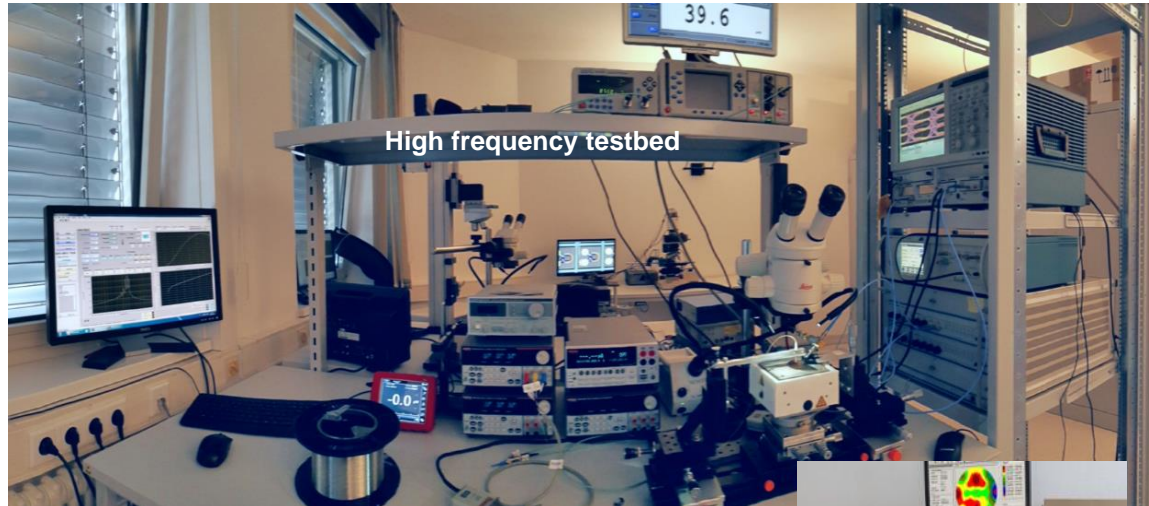
- 120 Gbit/s 4-PAM eyes
- 6-tap pre-emphasis
- Realized with VIS G3



U. Hecht et al ECOC 2019

High temperature, fast time response, reliability, high brightness are needed for sensing and automotive not less than for datacom

- **3D Modeling**
 - Opto-thermo-electric (drift diffusion)
- **Microscopy**
 - IR & visible light
- **Wafer mapping station**
 - Light-Current-Voltage
 - Optical Spectra
- **Static characterization**
 - Near Field, Far Field
 - CW, Pulsed,
 - Temperature,
- **High Frequency set up up to 128 Gb/s**
 - PAM2, PAM4
 - BER, S-parameters



This presentation was presented at EPIC World Photonics Technology Summit 2019

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